

PCN # 2136

DATE: March 11, 2021

EXPECTED PCN SHIP DATE: March 11, 2021



Quality Assurance
160 Rio Robles
San Jose, CA 95134

www.maximintegrated.com

PROCESS CHANGE NOTICE
 PRODUCT CHANGE NOTICE

MAXIM INTEGRATED HEREBY ISSUES NOTIFICATION OF CHANGE
THAT MAY AFFECT THE FOLLOWING CATEGORIES:

DESIGN WAFER FAB ASSEMBLY TEST ELEC/MECH SPECS

AFFECTED PRODUCT:

Ordering P/N: (See PN listing XLS in PCN ZIP file)

CHANGE FROM: - Maxim products in CSBGA package (Chip-scale ball grid array), Maxim package codes X25+1/X25+2 Current Assembler UTAC DONGGUAN LTD/Hong Kong (UDG)	CHANGE TO: - Additional assembly source Amkor Technology China/Shanghai (ATC)
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JUSTIFICATION: -
Bringing on assembler ATC is necessary to ensure supply flexibility and continuity as current vendor UDG is discontinuing the manufacturing of the Maxim package codes listed above by November 2021.
ATC qualification report is attached (ref. PCN 2136 ATC R40345FQ REL report).
There are no regulatory compliance changes to the material content of these devices
There are no changes to Form/Fit/Function at new assembler for these devices

TRACEABILITY: Maxim Integrated maintains full traceability by device marking, packaging labels and shipment documents.

Maxim Integrated's Change Notification System is designed to keep our customer base apprised of major product, manufacturing, or facility improvements.

Nasser Ali Chaouche

Nasser AliChaouche / PCN Coordinator

For further information, please contact either of the people listed below.

Contact your local Maxim Integrated Company Representative or Nasser AliChaouche, PCN Coordinator
408-601-5660 / pcn.coordinator@maximintegrated.com